

Features

- Select models are compliant with AEC-Q200 Rev-C Stress Test Qualification for Passive Components in Automotive Applications (see chart below)
- RoHS compliant*
- ESD protection >25 kV
- Low capacitance <0.5 pF
- Low leakage current <50 nA

Applications

- HDMI 1.4
- Digital Visual Interface (DVI)
- USB 3.0 / USB OTG
- Memory protection
- SIM card ports
- Automotive

ChipGuard® MLC Series - ESD Protectors

General Information

The ChipGuard® MLC Series has been specifically designed to protect sensitive electronic components from electrostatic discharge damage. The MLC family has been designed to protect equipment to IEC61000-4-2, Level 4 (±8 kV Contact / ±15 kV Air Discharge) ESD specifications targeted for high speed USB 3.0/USB OTG, HDMI 1.4, DVI or IEEE1394 applications.

The ChipGuard® MLC Series has been manufactured to provide low 0.5 pF capacitance and leakage currents less than 50 nA with excellent clamp qualities, making the family almost transparent under normal working conditions.

AEC Approved Models

| Model | AEC-Q200 | | | |
|---------------|----------|--|--|--|
| CG0603MLC-05E | ✓ Yes | | | |
| CG0603MLC-12E | ✓ Yes | | | |

Device Symbol



Electrical Characteristics @ 25 °C (unless otherwise noted)

| Dawamatan | Complete | CG0402MLC- | | | | | | | | 11 |
|--|----------|---------------------------|------|------|------|--------|----------------|-------|-------|------|
| Parameter | Symbol | 3.3LG | 05LG | 12LG | 24LG | 3.3LGA | 05LGA | 12LGA | 24LGA | Unit |
| Typical Continuous Operating Voltage | V_{DC} | 3.3 | 5 | 12 | 24 | 3.3 | 5 | 12 | 24 | V |
| Typical Clamping Voltage (Note 1) | ٧c | | | | 2 | 25 | | | | ٧ |
| Maximum Capacitance @ 1 VRMS 1 MHz | CO | | 0.5 | | | | | pF | | |
| Maximum Leakage Current @ Max. VDC | ΙL | 5 | | | | | nA | | | |
| Typical Trigger Voltage (Note 2) | VT | 250 | | | | | V | | | |
| Maximum Response Time | RT | 1 | | | | ns | | | | |
| ESD Protection: Per IEC 61000-4-2 Level 4 Min. Contact Discharge Min. Air Discharge Min. Air Discharge | | ±8 ±15 (Note 3) ±25 | | | | | kV kV kV | | | |
| Operating Temperature | TOPR | -40 to +85 -40 to +125 | | | | °C | | | | |
| Storage Temperature | TSTG | -55 to +150 | | | | °C | | | | |

| Developed | Cumbal | CG0603MLC- | | | | | | | | | Unit | |
|--|-----------------|---------------------------|-----|------|-----|----------------|------|--------|-------|-------|-------|------|
| Parameter | Symbol | 3.3LE | 05E | 05LE | 12E | 12LE | 24LE | 3.3LEA | 05LEA | 12LEA | 24LEA | Onit |
| Typical Continuous Operating Voltage | V _{DC} | 3.3 | 5 | 5 | 12 | 12 | 24 | 3.3 | 5 | 12 | 24 | V |
| Typical Clamping Voltage (Note 1) | ٧c | 25 | 20 | 25 | 30 | | | 2 | 25 | | | V |
| Maximum Capacitance @ 1 VRMS 1 MHz | CO | | | | | 0 | .5 | | | | | pF |
| Maximum Leakage Current @ Max. VDC | IL | 5 50 5 50 5 | | | | nA | | | | | | |
| Typical Trigger Voltage (Note 2) | ٧T | 250 150 250 150 250 | | | | V | | | | | | |
| Maximum Response Time | R _T | R _T 1 | | | | ns | | | | | | |
| ESD Protection: Per IEC 61000-4-2 Level 4 Min. Contact Discharge Min. Air Discharge Min. Air Discharge | | ±8 ±15 (Note 3) ±25 | | | | kV kV kV | | | | | | |
| Operating Temperature | TOPR | -40 to +85 -40 to +125 | | | °C | | | | | | | |
| Storage Temperature | TSTG | -55 to +150 | | | °C | | | | | | | |

Notes: 1. Per IEC 61000-4-2, Level 4 8 kV Contact Discharge. Measurement 30 ns after initiation of pulse.

- 2. Per IEC 61000-4-2, Level 4 8 kV Contact Discharge. Measurement at maximum pulse voltage.
- 3. IEC 61000-4-2 ESD Performance for CG0603MLC-05E and CG0603MLC-12E devices will meet minimum 100 reps. Some shifting in characteristics may occur when tested over several hundred ESD pulses. All other part numbers listed will meet IEC 61000-4-2 ESD Performance with minimum 1000 reps without degradation in performance.

*RoHS Directive 2002/95/EC Jan. 27, 2003 including annex and RoHS Recast 2011/65/EU June 8, 2011. Specifications are subject to change without notice.

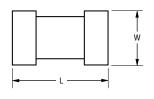
The device characteristics and parameters in this data sheet can and do vary in different applications and actual device performance may vary over time. Users should verify actual device performance in their specific applications.

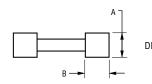
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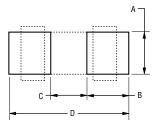
Recommended Pad Layout

Product Dimensions





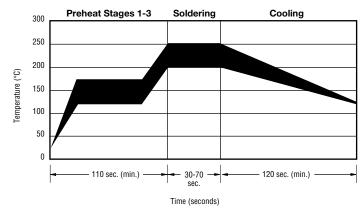
DIMENSIONS: $\frac{MM}{(INCHES)}$



| Dimension | CG0402 Series | CG0603 Series | | | | |
|-----------|---|---|--|--|--|--|
| L | $\frac{1.00 \pm 0.15}{(0.04 \pm 0.006)}$ | $\frac{1.60 \pm 0.20}{(0.064 \pm 0.008)}$ | | | | |
| W | $\frac{0.50 \pm 0.10}{(0.02 \pm 0.004)}$ | $\frac{0.80 \pm 0.20}{(0.032 \pm 0.008)}$ | | | | |
| A | $\frac{0.36 \pm 0.05}{(0.014 \pm 0.002)}$ | $\frac{0.45 \pm 0.10}{(0.018 \pm 0.004)}$ | | | | |
| В | $\frac{0.25 \pm 0.15}{(0.10 \pm 0.006)}$ | $\frac{0.30 \pm 0.20}{(0.012 \pm 0.008)}$ | | | | |

| Dim. | CG0402 Series | CG0603 Series | | | | |
|------|------------------------|------------------|--|--|--|--|
| А | <u>0.51</u> (0.020) | 0.76 (0.030) | | | | |
| В | <u>0.61</u> (0.024) | 1.02 (0.040) | | | | |
| С | <u>0.51</u> (0.020) | 0.50 (0.020) | | | | |
| D | 1.70 (0.067) | 2.54 (0.100) | | | | |

Solder Reflow Recommendations



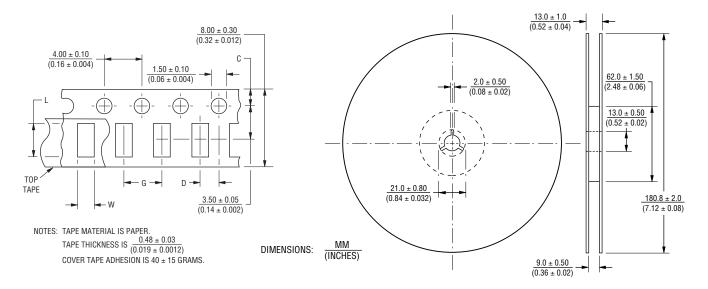
| Α | Stage 1 Preheat | Ambient to Preheating Temperature | 30 s to 60 s |
|---|-----------------|--|---|
| В | Stage 2 Preheat | 140 °C to 160 °C | 60 s to 120 s |
| С | Stage 3 Preheat | Preheat to 200 °C | 20 s to 40 s |
| D | Main Heating | 200 °C 210 °C 220 °C 230 °C 240 °C 250 °C to 255 °C | 60 s to 70 s 55 s to 65 s 50 s to 60 s 40 s to 50 s 30 s to 40 s 5 s |
| Е | Cooling | 200 °C to 100 °C | 1 °C/s to 4 °C/s |

- This product can be damaged by rapid heating, cooling or localized heating.
- Heat shocks should be avoided. Preheating and gradual cooling recommended.
- Excessive solder can damage the device. Print solder thickness of 150 to 200 um recommended.
- Solder gun tip temperature should be kept below 280 °C and should not touch the device directly. Contact should be less than 3 seconds.
 A solder gun under 30 watts is recommended.

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Packaging Dimensions



| Dimension | CG0402 Series | CG0603 Series | | | | |
|-----------|--|---|--|--|--|--|
| С | $\frac{1.75 \pm 0.05}{(0.04 \pm 0.002)}$ | $\frac{1.75 \pm 0.10}{(0.04 \pm 0.004)}$ | | | | |
| D | $\frac{2.00 \pm 0.02}{(0.08 \pm 0.0008)}$ | $\frac{2.00 \pm 0.05}{(0.08 \pm 0.002)}$ | | | | |
| L | $\frac{1.12 \pm 0.03}{(0.045 \pm 0.0012)}$ | $\frac{1.80 \pm 0.20}{(0.072 \pm 0.008)}$ | | | | |
| W | $\frac{0.62 \pm 0.03}{(0.025 \pm 0.0012)}$ | $\frac{0.90 \pm 0.20}{(0.036 \pm 0.008)}$ | | | | |
| G | $\frac{2.0 \pm 0.05}{(0.08 \pm 0.002)}$ | $\frac{4.0 \pm 0.05}{(0.16 \pm 0.002)}$ | | | | |

CG 0n0n MLC - n.n x x x ChipGuard® Product Designator Package Option 0402 = 0402 Package 0603 = 0603 Package Multilayer Series Designator Operating Voltage** 3.3 = 3.3 V 05 = 5 V 12 = 12 V 24 = 24 V Low Leakage Current Option L = Low Leakage Current Blank = Standard Product Tape & Reel Packaging E = 5,000 pcs. per reel (0603 Package) G = 10,000 pcs. per reel (0402 Package) Operating Temperature Option

Operating Temperature Option

A = Higher +125 °C Operating Temperature
Blank = Standard Product

** Only models lower than 10 volts require decimal point.

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